IEEE P802.11  
Wireless LANs

|  |  |  |  |  |
| --- | --- | --- | --- | --- |
| TGbe 2020 July to September teleconference minutes | | | | |
| Date: 2020-07-16 | | | | |
| Author(s): | | | | |
| Name | Affiliation | Address | Phone | email |
| Dennis Sundman | Ericsson |  |  | dennis.sundman@ericsson.com |
|  |  |  |  |  |

Abstract

This document contains the minutes for July to September 2020 TGbe teleconferences.

Revisions:

* Rev 0: Added references to MAC and PHY sessions held 13th and 15th of July. Added minutes for joint meeting the 16th of July.
* Rev1: Added references to MAC and PHY sessions held 20th to 29th of July. Added minutes for joint meeting the 30th of July.

# Monday 13 July 2020, 19:00 – 21:00 ET

Split PHY and MAC.

* MAC: <https://mentor.ieee.org/802.11/dcn/20/11-20-1079-05-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-july-and-september-2020.docx>
* PHY: <https://mentor.ieee.org/802.11/dcn/20/11-20-1093-03-00be-minutes-for-tgbe-phy-ad-hoc-cc-july-to-sept-2020.docx>

# Wednesday 15 July 2020, 10:00 – 12:00 ET

Only MAC.

* MAC: <https://mentor.ieee.org/802.11/dcn/20/11-20-1079-05-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-july-and-september-2020.docx>

# Thursday 16 July 2020, 11:30 – 13:00 ET

Introduction

1. The Chair, Alfred Asterjadhi (Qualcomm), calls the meeting to order at 11:32 ET. The Chair notifies that the agenda is 927r9.
2. IEEE 802 and 802.11 IPR policy and procedure. If anyone in this meeting is personally aware of the holder of any patent claims that are potentially essential to implementation of the proposed standard(s) under consideration by this group please speak up now. Nobody speaks/writes up.
3. Attendance reminder.
   * Participation slide: <https://mentor.ieee.org/802-ec/dcn/16/ec-16-0180-05-00EC-ieee-802-participation-slide.pptx>
   * Please record your attendance during the conference call by using the IMAT system:
     + 1) login to [imat](https://imat.ieee.org/attendance), 2) select “802.11 Telecons (<Month>)” entry, 3) select “C/LM/WG802.11 Attendance” entry, 4) click “TGbe <MAC/PHY/Joint> conference call that you are attending.
   * If you are unable to record the attendance via [IMAT](https://imat.ieee.org/attendance) then please send an e-mail to Dennis Sundman ([dennis.sundman@ericsson.com](mailto:dennis.sundman@ericsson.com)) and Alfred Asterjadhi ([aasterja@qti.qualcomm.com](mailto:aasterja@qti.qualcomm.com))
   * Please ensure that the following information is listed correctly when joining the call:
     + "[voter status] First Name Last Name (Affiliation)"
   * Participants reported in IMAT:

* Abouelseoud, Mohamed Sony Corporation
* Aboulmagd, Osama Huawei Technologies Co.,  Ltd
* Aio, Kosuke Sony Corporation
* Ansley, Carol CommScope
* Asterjadhi, Alfred Qualcomm Incorporated
* Au, Kwok Shum Huawei Technologies Co.,  Ltd
* B, Hari Ram NXP Semiconductors
* Baek, SunHee LG ELECTRONICS
* Bei, Jianwei NXP Semiconductors
* Bluschke, Andreas Signify
* Bredewoud, Albert Broadcom Corporation
* Cao, Rui NXP Semiconductors
* CHAN, YEE Facebook
* Chen, Xiaogang Intel
* Cheng, Paul MediaTek Inc.
* CHERIAN, GEORGE Qualcomm Incorporated
* Chitrakar, Rojan Panasonic Asia Pacific Pte Ltd.
* Choi, Jinsoo LG ELECTRONICS
* Chu, Liwen NXP Semiconductors
* CHUN, JINYOUNG LG ELECTRONICS
* Duan, Ruchen SAMSUNG
* Fang, Yonggang ZTE TX Inc
* feng, Shuling MediaTek Inc.
* Fischer, Matthew Broadcom Corporation
* Gan, Ming Huawei Technologies Co., Ltd
* Ghosh, Chittabrata Intel Corporation
* Grandhe, Niranjan NXP Semiconductors
* Grigat, Michael Deutsche Telekom AG
* GUIGNARD, Romain Canon Research Centre France
* Guo, Yuchen Huawei Technologies Co., Ltd
* Hamilton, Mark Ruckus/CommScope
* Han, Jonghun SAMSUNG
* Han, Zhiqiang ZTE Corporation
* Ho, Duncan Qualcomm Incorporated
* Hsiao, Ching-Wen MediaTek Inc.
* Hsieh, Hung-Tao MediaTek Inc.
* Hu, Chunyu Facebook
* Hu, Glenn Tencent
* Huang, Guogang  Huawei
* Jang, Insun LG ELECTRONICS
* Ji, Chenhe Huawei Technologies Co. Ltd
* Jiang, Jinjing Apple, Inc.
* Kain, Carl USDoT
* Kandala, Srinivas SAMSUNG
* Kedem, Oren Huawei Technologies Co. Ltd
* Khude, Nilesh NXP Semiconductors
* Kim, Jeongki LG ELECTRONICS
* Kim, Myeong-Jin SAMSUNG
* kim, namyeong LG ELECTRONICS
* Kim, Sang Gook LG ELECTRONICS
* Kim, Songhak Kaonmedia
* Kim, Youhan Qualcomm Incorporated
* Kishida, Akira Nippon Telegraph and Telephone Corporation (NTT)
* Klein, Arik Huawei Technologies Co. Ltd
* Kneckt, Jarkko Apple, Inc.
* Koc, Onur VESTEL ELEKTRONIK SANAYI VE TICARET ANONIM SIRKETI
* Kwon, Young Hoon NXP Semiconductors
* Lan, Zhou Broadcom Corporation
* Lee, Wookbong SAMSUNG
* Levitsky, Ilya IITP RAS
* Levy, Joseph InterDigital, Inc.
* Li, Yiqing Huawei Technologies Co. Ltd
* Li, Yunbo Huawei Technologies Co., Ltd
* Lim, Dong Guk LG ELECTRONICS
* Lin, Wei Huawei Technologies Co. Ltd
* Lindskog, Erik SAMSUNG
* Liu, Jianhan MediaTek Inc.
* Lopez, Miguel Ericsson AB
* Lou, Hanqing InterDigital, Inc.
* Lu, Liuming ZTE Corporation
* Luo, Chaoming Beijing OPPO telecommunications corp., ltd.
* Ma, Mengyao HUAWEI
* Memisoglu, Ebubekir Istanbul Medipol University; Vestel
* Mirfakhraei, Khashayar Cisco Systems, Inc.
* Monajemi, Pooya Cisco Systems, Inc.
* Murphy, Rick vLogic, Inc.
* NANDAGOPALAN, SAI SHANKAR Cypress Semiconductor Corporation
* Naribole, Sharan SAMSUNG
* Nezou, Patrice Canon Research Centre France
* noh, yujin Newracom Inc.
* Pare, Thomas MediaTek Inc.
* Park, Eunsung LG ELECTRONICS
* Park, Minyoung Intel Corporation
* Patil, Abhishek Qualcomm Incorporated
* Patwardhan, Gaurav Hewlett Packard Enterprise
* Petrick, Albert InterDigital, Inc.
* Pettersson, Charlie Ericsson AB
* Puducheri, Srinath Broadcom Corporation
* Raissinia, Alireza Qualcomm Incorporated
* Redlich, Oded HUAWEI
* RISON, Mark Samsung Cambridge Solution Centre
* Rosdahl, Jon Qualcomm Technologies, Inc.
* Roy, Sayak NXP Semiconductors
* Schelstraete, Sigurd Quantenna Communications, Inc.
* Sedin, Jonas Ericsson AB
* Seok, Yongho MediaTek Inc.
* Sethi, Ankit NXP Semiconductors
* Shellhammer, Stephen Qualcomm Incorporated
* Shilo, Shimi HUAWEI
* Singh, Gurdev SAMSUNG
* Solaija, Muhammad Sohaib Istanbul Medipol University; Vestel
* Song, Taewon LG ELECTRONICS
* Strauch, Paul Qualcomm Incorporated
* SUH, JUNG HOON Huawei Technologies Co. Ltd
* Sun, Bo ZTE Corporation
* Sun, Li-Hsiang InterDigital, Inc.
* Sun, Yanjun Qualcomm Incorporated
* Sundman, Dennis Ericsson AB
* SURACI, FRANK U.S. Department of Homeland Security
* Tanaka, Yusuke Sony Corporation
* Tian, Bin Qualcomm Incorporated
* Tsodik, Genadiy Huawei Technologies Co. Ltd
* Varshney, Prabodh Nokia
* Vermani, Sameer Qualcomm Incorporated
* VIGER, Pascal Canon Research Centre France
* Wang, Hao Tencent
* Wang, Huizhao Quantenna Communications, Inc.
* Wang, Lei Huawei R&D USA
* Wang, Qi Apple, Inc.
* Wang, Xiaofei InterDigital, Inc.
* Wendt, Matthias Signify
* Wentink, Menzo Qualcomm
* Wu, Tianyu Apple, Inc.
* Wullert, John Perspecta Labs
* Xin, Liangxiao Sony Corporation
* Xin, Yan Huawei Technologies Co., Ltd
* Yan, Aiguo Oppo
* YANG, RUI InterDigital, Inc.
* Yang, Steve TS MediaTek Inc.
* Yano, Kazuto Advanced Telecommunications Research Institute International (ATR)
* Yee, James MediaTek Inc.
* yi, yongjiang Futurewei Technologies
* Young, Christopher Broadcom Corporation
* Yu, Jian Huawei Technologies Co., Ltd
* Yukawa, Mitsuyoshi Canon, Inc.
* Zhang, Yan NXP Semiconductors
* Zuo, Xin Tencent

1. Comment regarding Agenda:
   1. C: I have an updated strawpoll on 1961.
   2. R: This was not submitted within 24 hours so we take it the next meeting.
   3. C: I want to defer 596
   4. C: I want to defer 617
   5. R: Ok.

Agenda approved with unanimous consent.

1. Announcements:
   1. Towards TGbe D0.1 Draft – Status and Updates
      * [997r4](https://mentor.ieee.org/802.11/dcn/20/11-20-0997-04-00be-tgbe-spec-text-volunteers-and-status.docx) TGbe spec text volunteers and status
      * Some discussion and clarifications regarding the spec text volunteers and status.
      * The chair updates the document live.
      * The chair explains the guidelines for R1 vs R2 categorization.
        + Comments:
          - C: We should not discuss R2 during R1 (for draft spec text).
          - C: Simple topics should be clear for R1.
          - C: Suggestion to follow motion of January for which topic falls in R1 and R2.
          - C: Should follow guidline as strictly as possible.
          - C: I prefer a 50% threshold for SPs.
          - C: If there are not many motions in a category then implicitly it should belong in R1.

Adjourned at 13:00 ET

# Thursday 20 July 2020, 10:00 – 13:00 ET

Split PHY and MAC.

* MAC: <https://mentor.ieee.org/802.11/dcn/20/11-20-1079-05-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-july-and-september-2020.docx>
* PHY: <https://mentor.ieee.org/802.11/dcn/20/11-20-1093-03-00be-minutes-for-tgbe-phy-ad-hoc-cc-july-to-sept-2020.docx>

# Thursday 22 July 2020, 10:00 – 13:00 ET

Only MAC.

* MAC: <https://mentor.ieee.org/802.11/dcn/20/11-20-1079-05-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-july-and-september-2020.docx>

# Thursday 23 July 2020, 10:00 – 13:00 ET

Split PHY and MAC.

* MAC: <https://mentor.ieee.org/802.11/dcn/20/11-20-1079-05-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-july-and-september-2020.docx>
* PHY: <https://mentor.ieee.org/802.11/dcn/20/11-20-1093-03-00be-minutes-for-tgbe-phy-ad-hoc-cc-july-to-sept-2020.docx>

# Thursday 27 July 2020, 10:00 – 13:00 ET

Split PHY and MAC.

* MAC: <https://mentor.ieee.org/802.11/dcn/20/11-20-1079-05-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-july-and-september-2020.docx>
* PHY: <https://mentor.ieee.org/802.11/dcn/20/11-20-1093-03-00be-minutes-for-tgbe-phy-ad-hoc-cc-july-to-sept-2020.docx>

# Thursday 29 July 2020, 10:00 – 13:00 ET

Only MAC.

* Not available yet.

# Thursday 30 July 2020, 10:00 – 13:00 ET

1. The Chair (Alfred Asterjadhi, Qualcomm) calls the meeting to order at 10:02. The agenda can be found in 927r15. A reminder that this call is one with motions.
2. IEEE 802 and 802.11 IPR policy and procedure. If anyone in this meeting is personally aware of the holder of any patent claims that are potentially essential to implementation of the proposed standard(s) under consideration by this group please speak up now. Nobody speaks/writes up.
3. Attendance reminder.
   * Participation slide: <https://mentor.ieee.org/802-ec/dcn/16/ec-16-0180-05-00EC-ieee-802-participation-slide.pptx>
   * Please record your attendance during the conference call by using the IMAT system:
     + 1) login to [imat](https://imat.ieee.org/attendance), 2) select “802.11 Telecons (<Month>)” entry, 3) select “C/LM/WG802.11 Attendance” entry, 4) click “TGbe <MAC/PHY/Joint> conference call that you are attending.
   * If you are unable to record the attendance via [IMAT](https://imat.ieee.org/attendance) then please send an e-mail to Dennis Sundman ([dennis.sundman@ericsson.com](mailto:dennis.sundman@ericsson.com)) and Alfred Asterjadhi ([aasterja@qti.qualcomm.com](mailto:aasterja@qti.qualcomm.com))
   * Please ensure that the following information is listed correctly when joining the call:
     + "[voter status] First Name Last Name (Affiliation)"
   * Participants reported in IMAT:

* Aboulmagd, Osama Huawei Technologies Co.,  Ltd
* Adhikari, Shubhodeep Broadcom Corporation
* Agarwal, Peyush Broadcom Corporation
* Aio, Kosuke Sony Corporation
* Alayasra, Musab Medipol University; Vestel
* An, Song-Haur INDEPENDENT
* Anwyl, Gary MediaTek Inc.
* Asterjadhi, Alfred Qualcomm Incorporated
* Au, Kwok Shum Huawei Technologies Co.,  Ltd
* B, Hari Ram NXP Semiconductors
* Baek, SunHee LG ELECTRONICS
* Baik, Eugene Qualcomm Incorporated
* Bankov, Dmitry IITP RAS
* Batra, Anuj Apple, Inc.
* Bhandaru, Nehru Broadcom Corporation
* Bredewoud, Albert Broadcom Corporation
* Cao, Rui NXP Semiconductors
* Carney, William Sony Corporation
* chen, jindou Huawei Technologies Co. Ltd
* Cheng, Paul MediaTek Inc.
* CHERIAN, GEORGE Qualcomm Incorporated
* Chu, Liwen NXP Semiconductors
* CHUN, JINYOUNG LG ELECTRONICS
* Coffey, John Realtek Semiconductor Corp.
* Das, Dibakar Intel Corporation
* Das, Subir Perspecta Labs Inc.
* Dash, Debashis Apple, Inc.
* Dave, Brajesh Apple, Inc.
* Dong, Xiandong Xiaomi Inc.
* Doostnejad, Roya Intel Corporation
* Duan, Ruchen SAMSUNG
* Fang, Yonggang ZTE TX Inc
* feng, Shuling MediaTek Inc.
* Fischer, Matthew Broadcom Corporation
* Ghaderipoor, Alireza MediaTek Inc.
* Ghosh, Chittabrata Intel Corporation
* Guo, Yuchen Huawei Technologies Co., Ltd
* Han, Jonghun SAMSUNG
* Han, Zhiqiang ZTE Corporation
* Handte, Thomas Sony Corporation
* Hervieu, Lili Cable Television Laboratories Inc. (CableLabs)
* Ho, Duncan Qualcomm Incorporated
* Hsieh, Hung-Tao MediaTek Inc.
* Hu, Chunyu Facebook
* Huang, Guogang  Huawei
* Huang, Lei Panasonic Asia Pacific Pte Ltd.
* Huang, Po-Kai Intel Corporation
* Hwang, Sung Hyun Electronics and Telecommunications Research Institute (ETRI)
* Jang, Insun LG ELECTRONICS
* Ji, Chenhe Huawei Technologies Co. Ltd
* Jia, Jia Huawei Technologies Co., Ltd
* jiang, feng Apple Inc.
* Jiang, Jinjing Apple, Inc.
* Kain, Carl USDoT
* Kakani, Naveen Qualcomm Incorporated
* Kamel, Mahmoud InterDigital, Inc.
* Kedem, Oren Huawei Technologies Co. Ltd
* Khorov, Evgeny IITP RAS
* Kim, Jeongki LG ELECTRONICS
* Kim, Myeong-Jin SAMSUNG
* kim, namyeong LG ELECTRONICS
* Kim, Sang Gook LG ELECTRONICS
* Klein, Arik Huawei Technologies Co. Ltd
* Klimakov, Andrey Huawei Technologies Co., Ltd
* Kneckt, Jarkko Apple, Inc.
* Ko, Geonjung WILUS Inc.
* Kondo, Yoshihisa Advanced Telecommunications Research Institute International (ATR)
* Kumar, Manish Marvell Semiconductor, Inc.
* Kwon, Young Hoon NXP Semiconductors
* Lalam, Massinissa SAGEMCOM BROADBAND SAS
* Lan, Zhou Broadcom Corporation
* Lansford, James Qualcomm Incorporated
* Latif, Imran Quantenna Communications, Inc.
* Lee, Wookbong SAMSUNG
* Levitsky, Ilya IITP RAS
* Levy, Joseph InterDigital, Inc.
* Li, Guoqing Apple, Inc.
* Li, Nan ZTE Corporation
* Li, Yunbo Huawei Technologies Co., Ltd
* Liang, dandan Huawei Technologies Co., Ltd
* Liu, Jianfei HUAWEI
* Liu, Jianhan MediaTek Inc.
* Liu, Yong Apple, Inc.
* Lopez, Miguel Ericsson AB
* Lou, Hanqing InterDigital, Inc.
* Lu, Liuming ZTE Corporation
* Luo, Chaoming Beijing OPPO telecommunications corp., ltd.
* Lv, kaiying MediaTek Inc.
* Ma, Li MediaTek Inc.
* Ma, Mengyao HUAWEI
* Max, Sebastian Ericsson AB
* Mirfakhraei, Khashayar Cisco Systems, Inc.
* Monajemi, Pooya Cisco Systems, Inc.
* Montreuil, Leo Broadcom Corporation
* Nguyen, An DHS/CISA
* noh, yujin Newracom Inc.
* Palm, Stephen Broadcom Corporation
* Pare, Thomas MediaTek Inc.
* Park, Eunsung LG ELECTRONICS
* Park, Minyoung Intel Corporation
* Patil, Abhishek Qualcomm Incorporated
* Patwardhan, Gaurav Hewlett Packard Enterprise
* Petrick, Albert InterDigital, Inc.
* Puducheri, Srinath Broadcom Corporation
* Pulikkoonattu, Rethnakaran Broadcom Corporation
* Rai, Kapil Qualcomm Incorporated
* Redlich, Oded HUAWEI
* Rezk, Meriam Qualcomm Incorporated
* Rosdahl, Jon Qualcomm Technologies, Inc.
* Roy, Sayak NXP Semiconductors
* Sambasivan, Sam AT&T
* Sedin, Jonas Ericsson AB
* Seok, Yongho MediaTek Inc.
* Sethi, Ankit NXP Semiconductors
* Shilo, Shimi HUAWEI
* Solaija, Muhammad Sohaib Istanbul Medipol University; Vestel
* Song, Taewon LG ELECTRONICS
* Stanley, Dorothy Hewlett Packard Enterprise
* Startsev, Ivan IITP RAS
* SUH, JUNG HOON Huawei Technologies Co. Ltd
* Sun, Bo ZTE Corporation
* Sun, Li-Hsiang InterDigital, Inc.
* Sun, Yanjun Qualcomm Incorporated
* Sundman, Dennis Ericsson AB
* SURACI, FRANK U.S. Department of Homeland Security
* Tanaka, Yusuke Sony Corporation
* Tian, Bin Qualcomm Incorporated
* Tsodik, Genadiy Huawei Technologies Co. Ltd
* Urabe, Yoshio Panasonic Corporation
* Varshney, Prabodh Nokia
* Verenzuela, Daniel Sony Corporation
* Verma, Lochan Qualcomm Incorporated
* Verma, Sindhu Broadcom Corporation
* Vermani, Sameer Qualcomm Incorporated
* Wang, Chao Chun MediaTek Inc.
* Wang, Hao Tencent
* Wang, Huizhao Quantenna Communications, Inc.
* Wang, Lei Huawei R&D USA
* Wang, Qi Apple, Inc.
* Wu, Kanke Qualcomm Incorporated
* Wu, Tianyu Apple, Inc.
* Wullert, John Perspecta Labs
* Xin, Yan Huawei Technologies Co., Ltd
* Yan, Aiguo Oppo
* Yang, Jay Nokia
* YANG, RUI InterDigital, Inc.
* Yang, Steve TS MediaTek Inc.
* Yano, Kazuto Advanced Telecommunications Research Institute International (ATR)
* Yee, James MediaTek Inc.
* yi, yongjiang Futurewei Technologies
* Yona, Yair Qualcomm Incorporated
* Yong, Su Khiong Apple, Inc.
* Young, Christopher Broadcom Corporation
* Yu, Jian Huawei Technologies Co., Ltd
* Yukawa, Mitsuyoshi Canon, Inc.
* Zein, Nader NEC Laboratories Europe
* Zeng, Yan Huawei Technologies Co.,  Ltd
* Zhang, Yan NXP Semiconductors
* Zuo, Xin Tencent

1. Announcements: Nothing mentioned.
2. Any objection to proceed with the agenda?

C: For the 1961r4, can we defer it to the end of MAP General? 🡪 ok.

C: What is the idea for the D0.1 – Status and Updates discussion? 🡪 The idea is to finalize the joint items as well as going through the yellow parts.

C: The agenda is approved.

**Motions (concentrated within the first 90 mins of the call) in document** [**841r12**](https://mentor.ieee.org/802.11/dcn/20/11-20-0841-12-00be-tgbe-motions-list-for-teleconferences.pptx)

1. **Approve TG minutes.**

**Move to approve TGbe minutes of teleconferences listed below:**

* + **Teleconferences May-July:**

[**https://mentor.ieee.org/802.11/dcn/20/11-20-0775-06-00be-may-july-tgbe-teleconference-minutes.docx**](https://mentor.ieee.org/802.11/dcn/20/11-20-0775-06-00be-may-july-tgbe-teleconference-minutes.docx)

**Move:** Dennis Sundman, Second: Edward Au

**Discussion:** No discussion.

Approved with unanimous consent.

1. **Motion 119.**

**Move to add to the 11be SFD, candidate specification text in 11-20/566r44 that is identified with the following tags:**

* + SP103, SP104, SP105, SP106, SP107, SP108, SP109, SP110, SP111, SP112, SP113, SP114, SP115, SP116, SP117, SP118, SP119, SP120, SP121, SP122, SP123, SP124, SP125, SP126, SP127, SP128, SP129, SP130.

Move: Edward Au, Second: Stephen (Kiwin) Palm

**Discussion:** No discussion.

Approved with unanimous consent.

1. **Motion 120. (Amended by motion 121)**

**Move to add to the 11be SFD the following text:**

* **11be agrees to define mechanisms to support the operation of a Non-STR AP MLD in R1**
* **The mechanisms are limited to instantiate a Non-STR Non-AP MLD as a Soft AP that could utilize all its links. The exact language to govern such scope is TBD.**

**Move:** Jinjing Jian, **Second:** Kaiying Lu

**Discussion:**

C: The Non-STR AP adds complexity to the spec text of R1. I also question the use case for this to be part of R1.

C: There is probably needed to put some definition of Soft AP. Probably the node part of this text should be put as informative part.

C: A Soft AP should be simplified as an MLD.

C: I would like to move to make a motion to amend the motion to remove the “Note:”. See **Motion 121**. 🡪 Motion amended.

Preliminary Results: Y/N/Abstain/no-vote: 85/32/24/57 🡪 preliminary fails.

1. **Motion 121.**

Move to amend Motion 120 by deleting the following term: “Note:”.

Move: Zhou Lan, Second: Yong Liu

Discission: No discussion.

Preliminary results: Y/N/Abstain/no-vote: 98/15/24/61 🡪 preliminary passes.

**Towards TGbe D0.1 Draft – Status and Updates [~30 mins]**

[997r9](https://mentor.ieee.org/802.11/dcn/20/11-20-0997-09-00be-tgbe-spec-text-volunteers-and-status.docx) TGbe spec text volunteers and status.

* 1. Updates to the document where cell-rows are marked green and release information is updated. The changes will be seen in r9.
  2. Extensive discussion regarding R1/R2 for MAP-Setup.
  3. **Straw poll:** R1 vs R2 SP: Do you support that MAP-setup is classified as R1?

**Result:** Y/N/A: 48/46/20.

* 1. **Straw poll:** Do you support having MAP-access and TXOP sharing topic under R1 spec development?

**Result:** Y/N/A: 52/59/13.

* 1. **Straw poll:** R1 vs R2 SP 3: Do you support having MAP-Group Management topic under R1 spec development?

**Result:** Y/N/A: 48/56/18.

* 1. **Straw poll:** SP4: Which option do you prefer: option 1: All MAP features in R1 (unless those already decided to be in R2), option 2: all MAP features in R2, option 3: abstain

**Result:** Y/N/A: 53/58/17.

**Technical submissions – Straw polls**

1. [**0674r3**](https://mentor.ieee.org/802.11/dcn/20/11-20-0674-03-00be-forward-compatible-ofdma.pptx)**, “Forward compatible OFDMA” – Xiaogang Chen (Intel)**

**SP**

**Do you agree that 11be support the design of allowing multiplexing STAs of different amendments in one transmissions with OFDMA?**

* + STAs of different amendments may include HE, EHT and post-EHT STA;
    - The BW allocated to different STAs that can be mixed in one transmission is TBD;
  + This feature is targeted for R2.

**Discussion:**

C: Can you modify the text and put post-EHT to its own bullet. 🡪 Ok.

C: Can you delete the s in transmission(s)? 🡪 Ok.

C: Can you add “…OFDMA using frequency domain A-PPDU”? 🡪 Ok.

New text:

**Do you agree that 11be support the design of allowing multiplexing STAs of different amendments in one transmission with OFDMA using frequency domain A-PPDU?**

* + STAs of different amendments may include HE, EHT
    - post-EHT STA is TBD;
    - The BW allocated to different STAs that can be mixed in one transmission is TBD;
  + This feature is targeted for R2.

**Result:** Y/N/A/no-answer: 88/1/36/51

1. [**0617r3**](https://mentor.ieee.org/802.11/dcn/20/11-20-0617-03-00be-multi-ap-operation-basic-definition.pptx)**, “Multi-AP Operation - Basic Definition” – Oren Kedem (Huawei)**

**Straw poll 1**

Which of the options do you prefer with regards to Multi-AP set definition?

* + - Option1 – One Static group “Multi-AP Candidate Set”
    - Option 2 – Two groups, one static “Multi-AP Candidate Set” and one Dynamic group “Multi AP Operation/Active Set”

Discussion:

C: We already have AP Candidate Set in the SFD. I think we need the dynamic group.

C: Dynamic group per TXOP means too much overhead.

C: Is this R1 or R2?

A: I don’t want to specify that.

C: Can we clarify that this is not intended for the SFD?

Running out of time, we will continue next session.

**Adjourned at 12:59.**